ABSTRACT

THERMALLY ENHANCED STACKED DIE PACKAGE

A stacked die design, and a method of forming the same, comprising: a substrate having a lower surface and an upper surface; a lower die connected to the substrate; a thermally conductive metal interposer thermally connected to the lower die and/or the substrate; and an upper die thermally connected to the metal interposer. The lower die and the upper die being spaced apart and comprising a stacked die whereby any heat generated by the upper die is transferred to the substrate by the metal interposer. (Fig. 1)